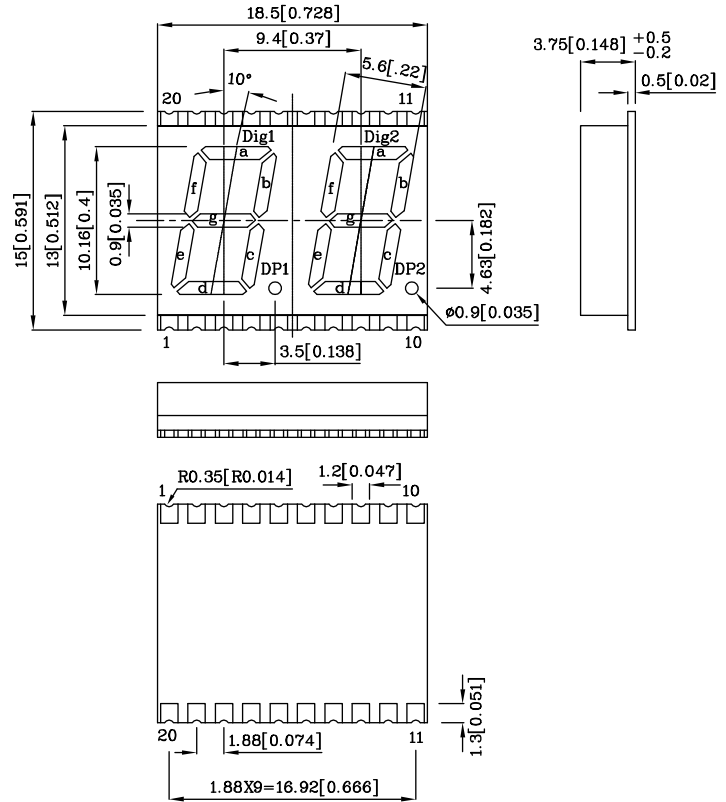
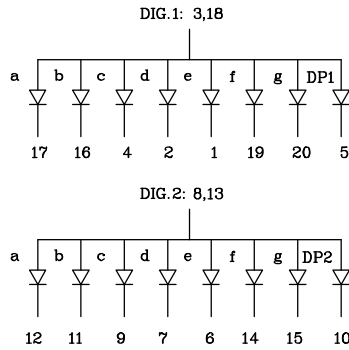


Features

- 0.4INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- GRAY FACE,WHITE SEGMENT.
- PACKAGE:500PCS/REEL.
- RoHS COMPLIANT.



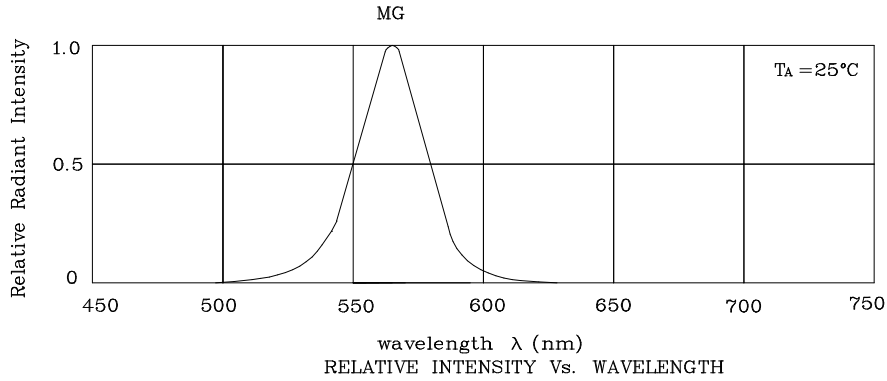
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.

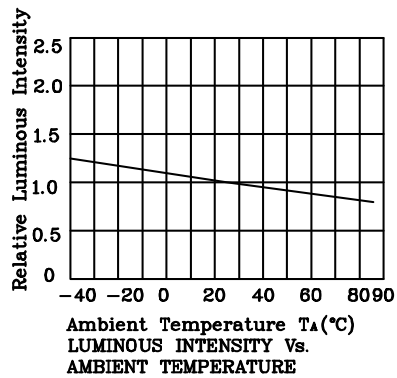
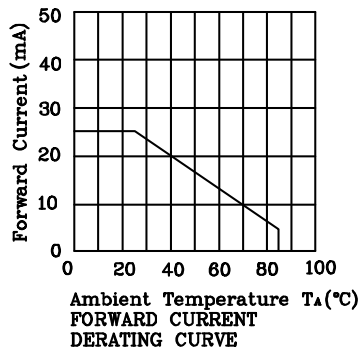
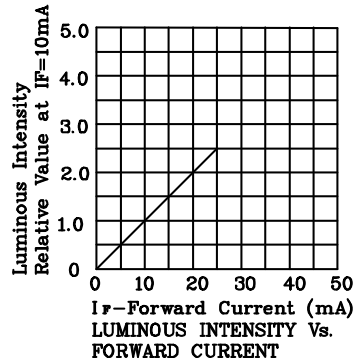
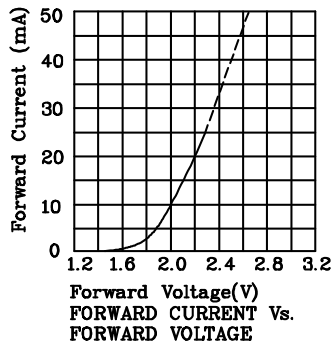
Absolute Maximum Ratings (TA=25°C)		MG (GaP)	Unit
Reverse Voltage	VR	5	V
Forward Current	IF	25	mA
Forward Current (peak) 1/10 Duty Cycle 0.1ms Pulse Width	iFS	140	mA
Power Dissipation	PT	105	mW
Operating Temperature	TA	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +85	

Operating Characteristics (TA=25°C)		MG (GaP)	Unit
Forward Voltage (typ.) (IF=10mA)	VF	2.0	V
Forward Voltage (max.) (IF=10mA)	VF	2.5	V
Reverse Current (VR=5V)	IR	10	uA
Wavelength of Peak Emission (IF=10mA)	λP	565	nm
Wavelength of Dominant Emission (IF=10mA)	λD	568	nm
Spectral Line Full Width At Half-Maximum (IF=10mA)	$\Delta\lambda$	30	nm
Capacitance (VF=0V, f=1MHz)	C	15	pF

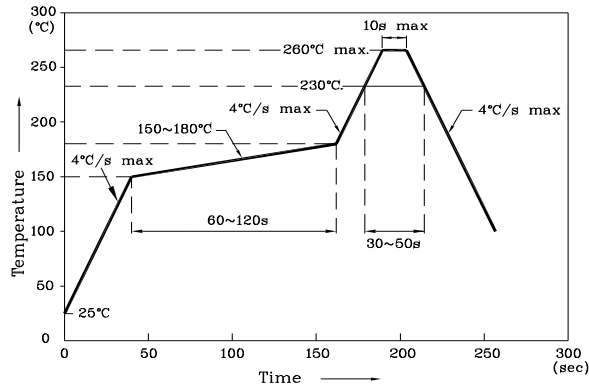
Part Number	Emitting Color	Emitting Material	Luminous Intensity (IF=10mA) ucd		Wavelength nm λP	Description
			min.	typ.		
XZDMG10A2	Green	GaP	1900	6990	565	Common Anode. Rt. Hand Decimal



❖ MG



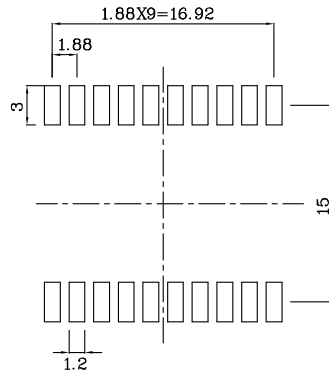
Reflow Soldering Profile For Lead-free SMT Process.



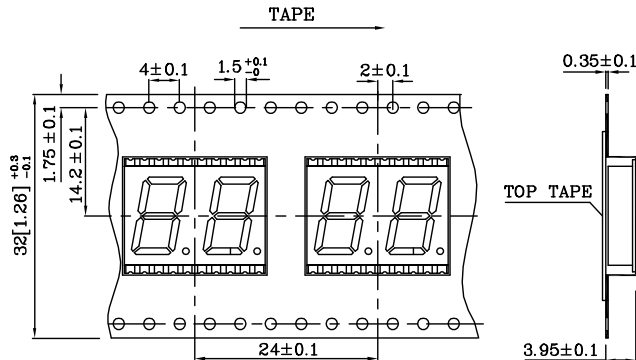
Notes:

1. Maximum soldering temperature should not exceed 260°C.
2. Recommended reflow temperature: 145°C-260°C.
3. Do not put stress to the epoxy resin during high temperatures conditions.

❖ Recommended Soldering Pattern (Units : mm;Tolerance:± 0.15)



❖ Tape Specification (Units : mm)



Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity, or wavelength), the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity: +/-15%
3. Forward Voltage: +/-0.1V

Note: Accuracy may depend on the sorting parameters.